Minsoo Kim

List of Publications by Year in descending order

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		1307594	1474206	
13	100	7	9	
papers	citations	h-index	g-index	
13	13	13	101	
all docs	docs citations	times ranked	citing authors	

#	Article	IF	CITATIONS
1	Lithographically patterned polypyrrole multilayer microstructures via sidewall-controlled electropolymerization. Journal of Micromechanics and Microengineering, 2021, 31, 025008.	2.6	2
2	Non-lithographic and scalable fabrication of one-turn-like inductor having laminated NiFe core for power converters operating at high frequency. , 2021, , .		0
3	Fully Additive Fabrication of Electrically Anisotropic Multilayer Materials Based on Sequential Electrodeposition. Journal of Microelectromechanical Systems, 2020, 29, 1510-1517.	2.5	7
4	Interlamination Insulation Design Considerations for Laminated Magnetics Operating at High Frequencies. IEEE Transactions on Magnetics, 2019, 55, 1-11.	2.1	3
5	Composite materials with controllable macromechanical properties based on MEMS-assisted structural manipulation of low-dimensional subcomponents., 2017,,.		2
6	Nanolaminated CoNiFe Cores with Dip-Coated Fluoroacrylic Polymer Interlamination Insulation: Fabrication, Electrical Characterization, and Performance Reliability., 2017,,.		4
7	Thick Multilayered Micromachined Permanent Magnets With Preserved Magnetic Properties. Journal of Microelectromechanical Systems, 2016, 25, 498-507.	2.5	9
8	Electrodeposited Nanolaminated CoNiFe Cores for Ultracompact DC–DC Power Conversion. IEEE Transactions on Power Electronics, 2015, 30, 5078-5087.	7.9	8
9	Silicon-Embedding Approaches to 3-D Toroidal Inductor Fabrication. Journal of Microelectromechanical Systems, 2013, 22, 580-588.	2.5	18
10	Monolithically-fabricated laminated inductors with electrodeposited silver windings. , 2013, , .		5
11	Nanolaminated Permalloy Core for High-Flux, High-Frequency Ultracompact Power Conversion. IEEE Transactions on Power Electronics, 2013, 28, 4376-4383.	7.9	26
12	Highly Laminated Soft Magnetic Electroplated CoNiFe Thick Films. IEEE Magnetics Letters, 2013, 4, 5000204-5000204.	1.1	7
13	A MEMS lamination technology based on sequential multilayer electrodeposition. Journal of Micromechanics and Microengineering, 2013, 23, 095011.	2.6	9